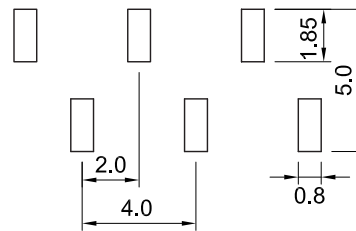
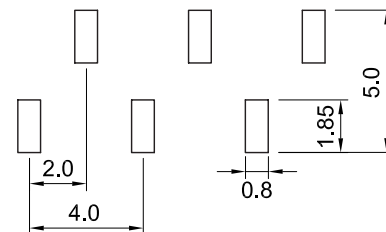


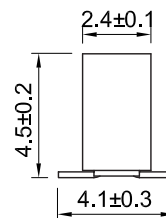
Recommended P.C. Board SMD Layout



A-Type



B-Type



* Contact Plating Option	Full Gold Plating	Gold Plated on Contact Area Tin Plated on Solder Area	Full Tin Plating
	G : Gold Flash G10: Gold 10u" G15: Gold 15u" G30: Gold 30u"	S: Gold Flash S10: Gold 10u" S15: Gold 15u" S30: Gold 30u"	T: Tin 100u"

General Tolerance	
X. ± 0.50	X.° ± 5°
.X ± 0.20	.X° ± 2°
.XX ± 0.10	.XX° ± 1°
Units : mm	

Specifications

- Current Rating: 2 Amps
- Insulator Resistance: 1000 Megohms min.
- Contact Resistance: 20 m ohms max.
- Dielectric Withstanding: AC 500V
- Operating Temperature : -40°C ~ +125°C
- Contact Material: Phosphor Bronze
- Insulator Material: Polyester, UL 94V-0, Nylon-6T
- Contact Plated: See Option / Standard = Full Gold Flash

Part Numbering System

FH200C-H4.3W2.4T4.1SS X - XX X X X X

- Series** _____
- Pin Layout Type:** _____
A = A Type
B = B Type
- No. of Pins** _____
- Contact Plating** _____
- Cap Option:** _____
Nil = No Cap
F = Film
M = Metal Cap
P = Plastic Cap
- Packing Method:** _____
B = Tube
T = Tape and Reel
- Insulator Material:** _____
N = High Temperature Nylon-6T